



US00D826189S

(12) **United States Design Patent**  
**Podubni**

(10) **Patent No.:** **US D826,189 S**

(45) **Date of Patent:** **\*\* Aug. 21, 2018**

- (54) **MODULAR CIRCUIT BOARD**
- (71) Applicant: **Tiny PCB, Inc.**, San Jose, CA (US)
- (72) Inventor: **Edward Podubni**, San Jose, CA (US)
- (73) Assignee: **TinyPCB, Inc.**
- (\*\*) Term: **15 Years**
- (21) Appl. No.: **29/605,593**
- (22) Filed: **May 26, 2017**
- (51) **LOC (11) Cl.** ..... **13-03**
- (52) **U.S. Cl.**  
USPC ..... **D13/182**
- (58) **Field of Classification Search**  
USPC ..... D13/182; 174/68.1, 250, 253, 255, 256;  
318/567, 568.1; 361/600, 601, 718, 719,  
361/720, 728, 736, 748, 751, 752, 760,  
361/761, 807; 439/55, 65, 68, 76.1, 92,  
439/93, 95  
CPC ..... H05K 3/00; H05K 3/30; H05K 3/301;  
H05K 3/303; H05K 3/34; H05K 3/3405;  
H05K 3/341; H05K 3/36; H05K 3/361;  
H05K 3/363; H05K 3/40; H05K 7/14;  
H05K 7/1422; H05K 7/00; H05K 1/18;  
H05K 1/02; H05K 1/181; H05K 1/182;  
H05K 1/183; H05K 1/184; H05K 1/189;  
H05K 1/00  
See application file for complete search history.

- (56) **References Cited**  
U.S. PATENT DOCUMENTS  
2,896,033 A \* 7/1959 Hartz ..... H01H 19/585  
200/11 D  
3,072,734 A \* 1/1963 Fox ..... H02B 1/043  
174/254  
D279,670 S \* 7/1985 Lukits ..... D13/182  
4,602,271 A \* 7/1986 Dougherty, Jr. .... H01L 23/5385  
257/697

- 4,715,928 A \* 12/1987 Hamby ..... H05K 3/4691  
156/150  
D319,045 S \* 8/1991 Hasegawa ..... D13/182  
D319,629 S \* 9/1991 Hasegawa ..... D13/182  
D319,814 S \* 9/1991 Hasegawa ..... D13/182  
D397,093 S \* 8/1998 Kim ..... D13/182  
5,895,967 A \* 4/1999 Stearns ..... H01L 23/3128  
257/691  
D429,704 S \* 8/2000 Kang ..... D13/182  
6,121,554 A \* 9/2000 Kamikawa ..... H05K 1/113  
174/255  
D440,209 S \* 4/2001 Kang ..... D13/182  
D442,149 S \* 5/2001 Kang ..... D13/182  
D442,150 S \* 5/2001 Kang ..... D13/182  
D442,567 S \* 5/2001 Kang ..... D13/182  
D457,146 S \* 5/2002 Yamamoto ..... D13/182  
6,418,030 B1 \* 7/2002 Yamaguchi ..... H01L 23/24  
257/698  
6,462,570 B1 10/2002 Price et al.  
D466,093 S \* 11/2002 Ebihara ..... D13/182  
D471,167 S \* 3/2003 Ebihara ..... D13/182

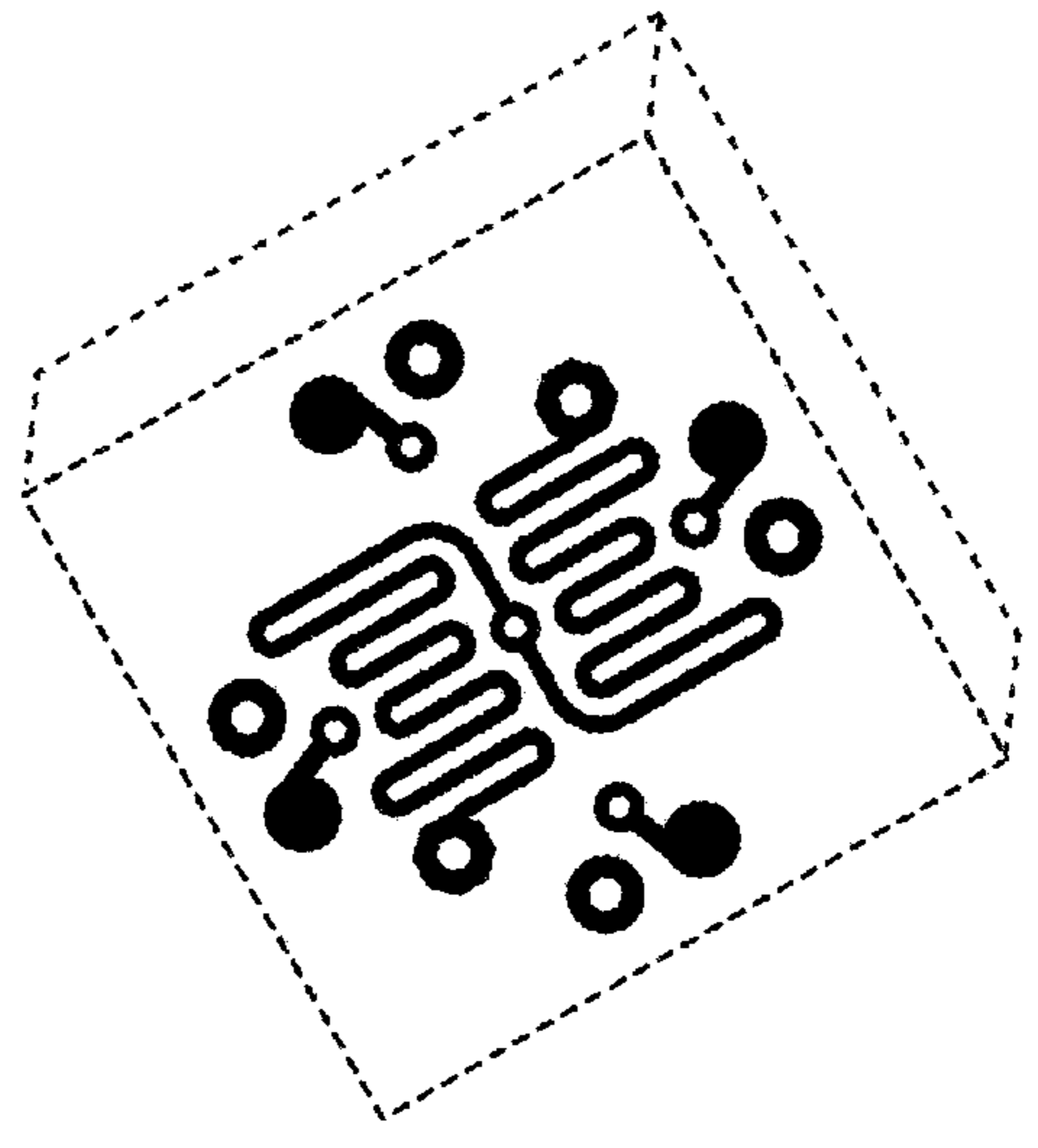
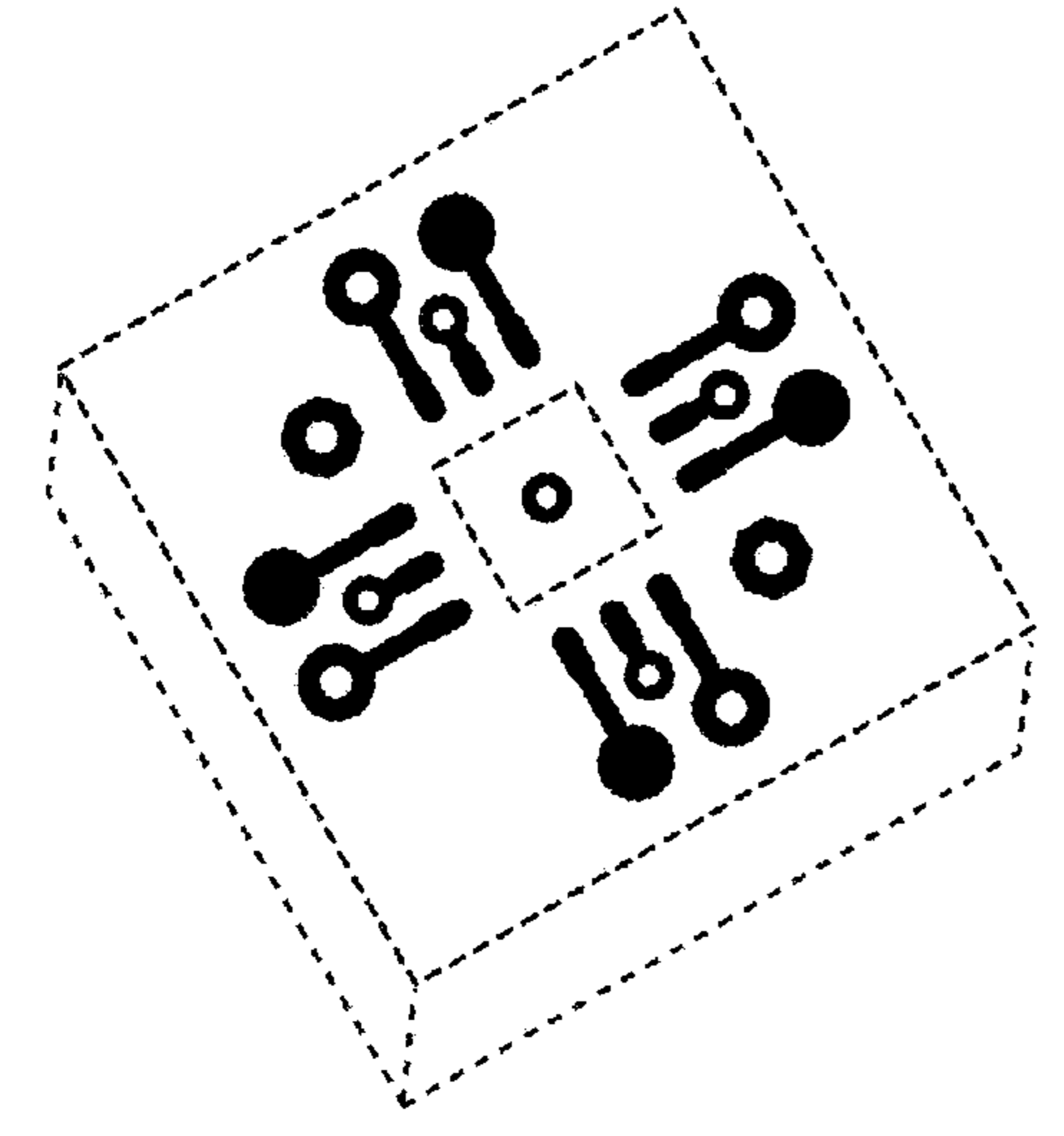
(Continued)

*Primary Examiner* — Elizabeth J Oswecki  
(74) *Attorney, Agent, or Firm* — Cooley LLP

(57) **CLAIM**  
The ornamental design for a modular circuit board, as shown and described.

**DESCRIPTION**  
FIG. 1 is a top perspective view of a modular circuit board, showing my new design;  
FIG. 2 is a bottom perspective view thereof;  
FIG. 3 is a top view thereof;  
FIG. 4 is a bottom view thereof; and,  
FIG. 5 is a side view thereof, all other side views being a mirror image thereof.  
The broken lines shown in the drawings represent portions of the modular circuit board that form no part of the claimed design.

**1 Claim, 5 Drawing Sheets**



(56)

References Cited

U.S. PATENT DOCUMENTS

D474,773	S *	5/2003	Kondo	.....	D13/182
D485,536	S *	1/2004	Dang	.....	D13/182
6,936,916	B2 *	8/2005	Moxham	.....	H01L 23/13 174/256
D552,048	S *	10/2007	He	.....	D13/182
D556,158	S *	11/2007	Kong	.....	D13/182
7,511,228	B2	3/2009	Yaung et al.		
D599,308	S *	9/2009	Blumberg, Jr.	.....	D13/182
D605,613	S *	12/2009	Carter	.....	D13/182
D639,756	S *	6/2011	Greene, Jr.	.....	D13/182
D642,546	S *	8/2011	Greene, Jr.	.....	D13/182
D645,039	S *	9/2011	Chen	.....	D14/341
8,113,888	B2 *	2/2012	Carter	.....	H01R 9/03 439/676
D676,004	S *	2/2013	Lyubachev	.....	D13/182
D699,201	S *	2/2014	Petsch	.....	D13/182
D768,115	S *	10/2016	Kazanchian	.....	D13/182
D794,586	S *	8/2017	Takahashi	.....	D13/182
D799,438	S *	10/2017	Takahashi	.....	D13/182
D804,437	S *	12/2017	Kantor	.....	D13/182
2006/0044765	A1 *	3/2006	Chen	.....	H05K 1/0206 361/720
2007/0205017	A1 *	9/2007	Takakusaki	.....	H05K 3/244 174/260
2008/0080151	A1 *	4/2008	Shimizu	.....	H05K 1/0263 361/760
2009/0250246	A1	10/2009	Yaung et al.		
2009/0268390	A1 *	10/2009	King	.....	G06F 13/409 361/679.33

\* cited by examiner

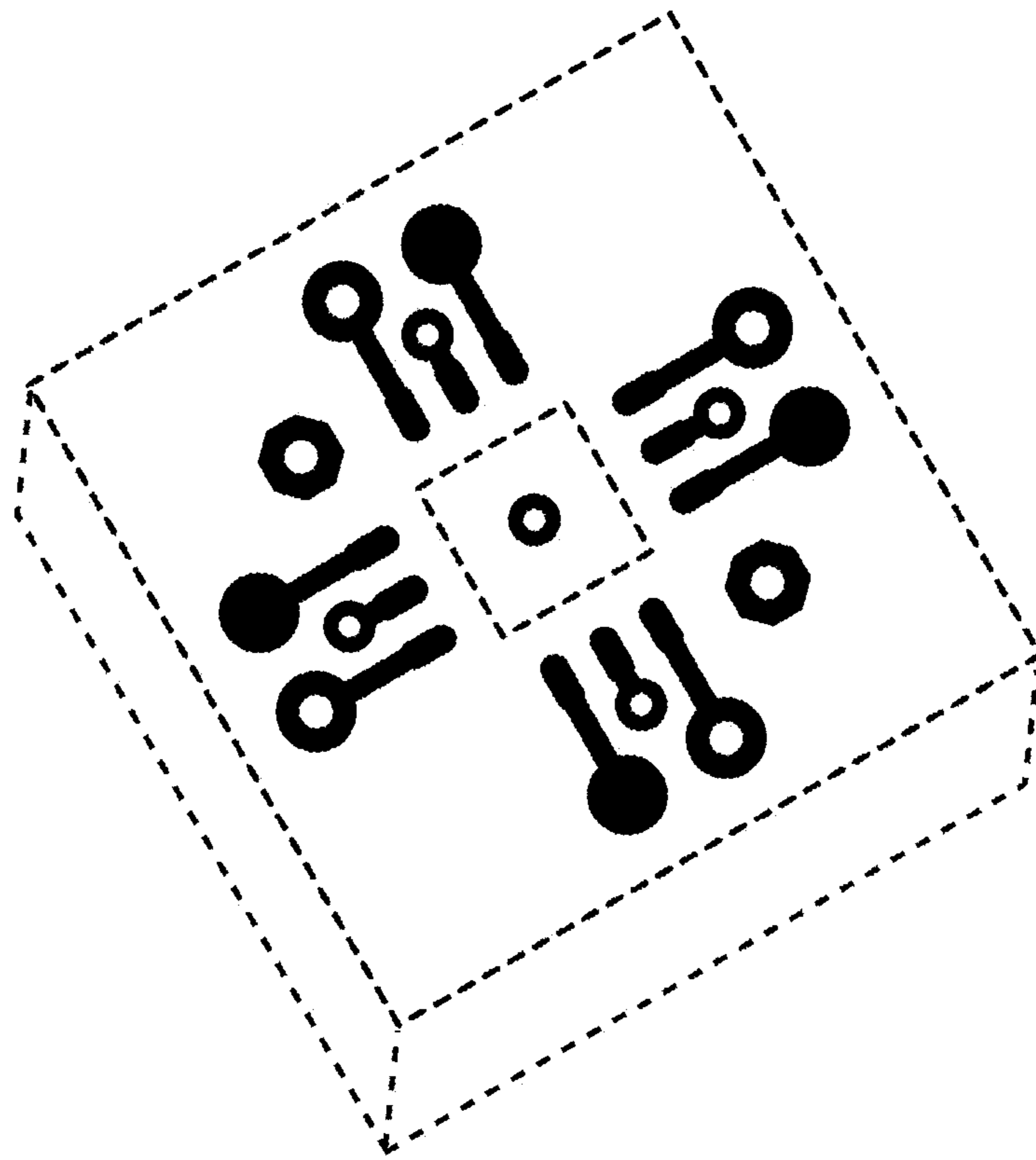


FIG. 1

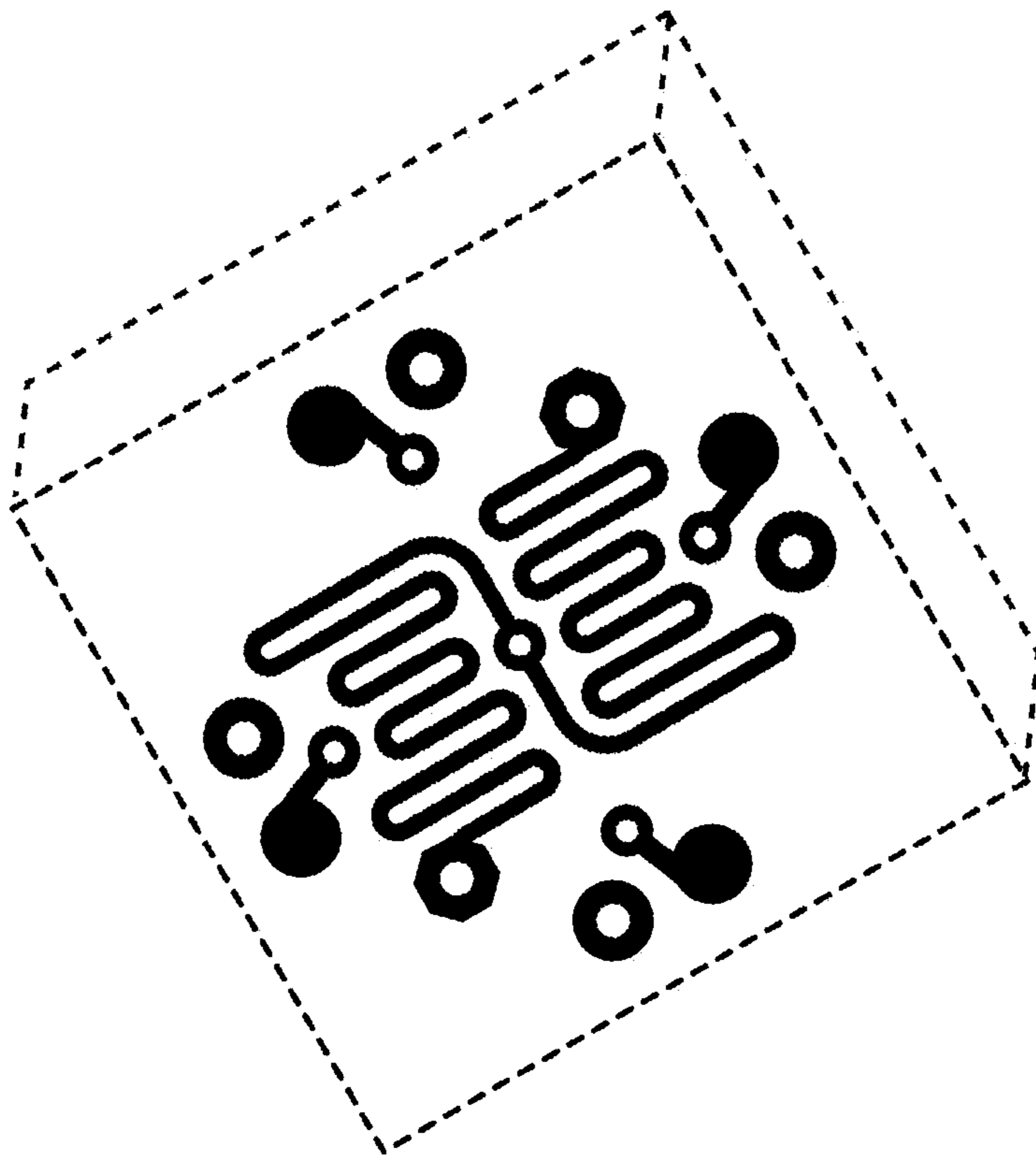


FIG. 2

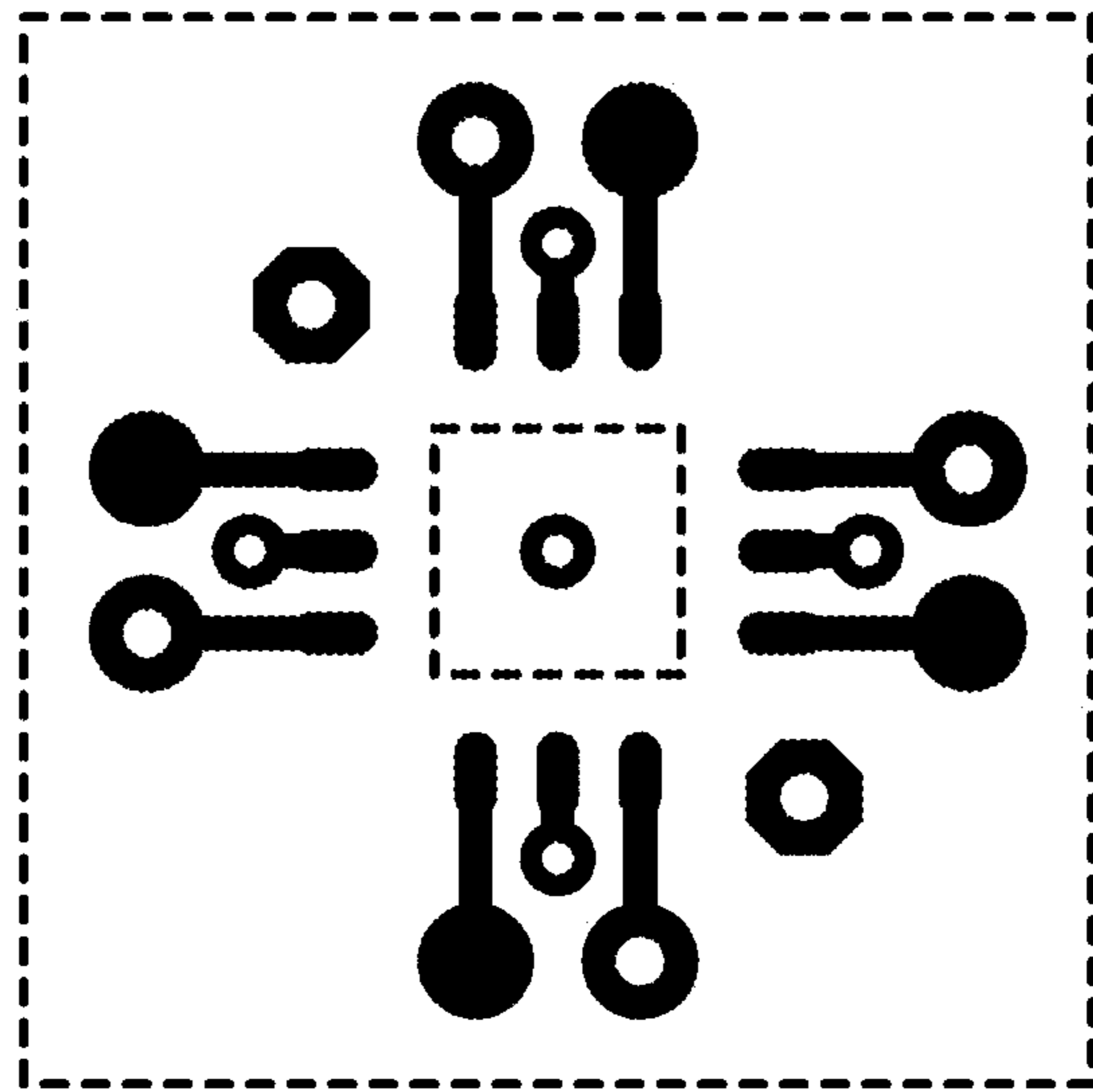


FIG. 3

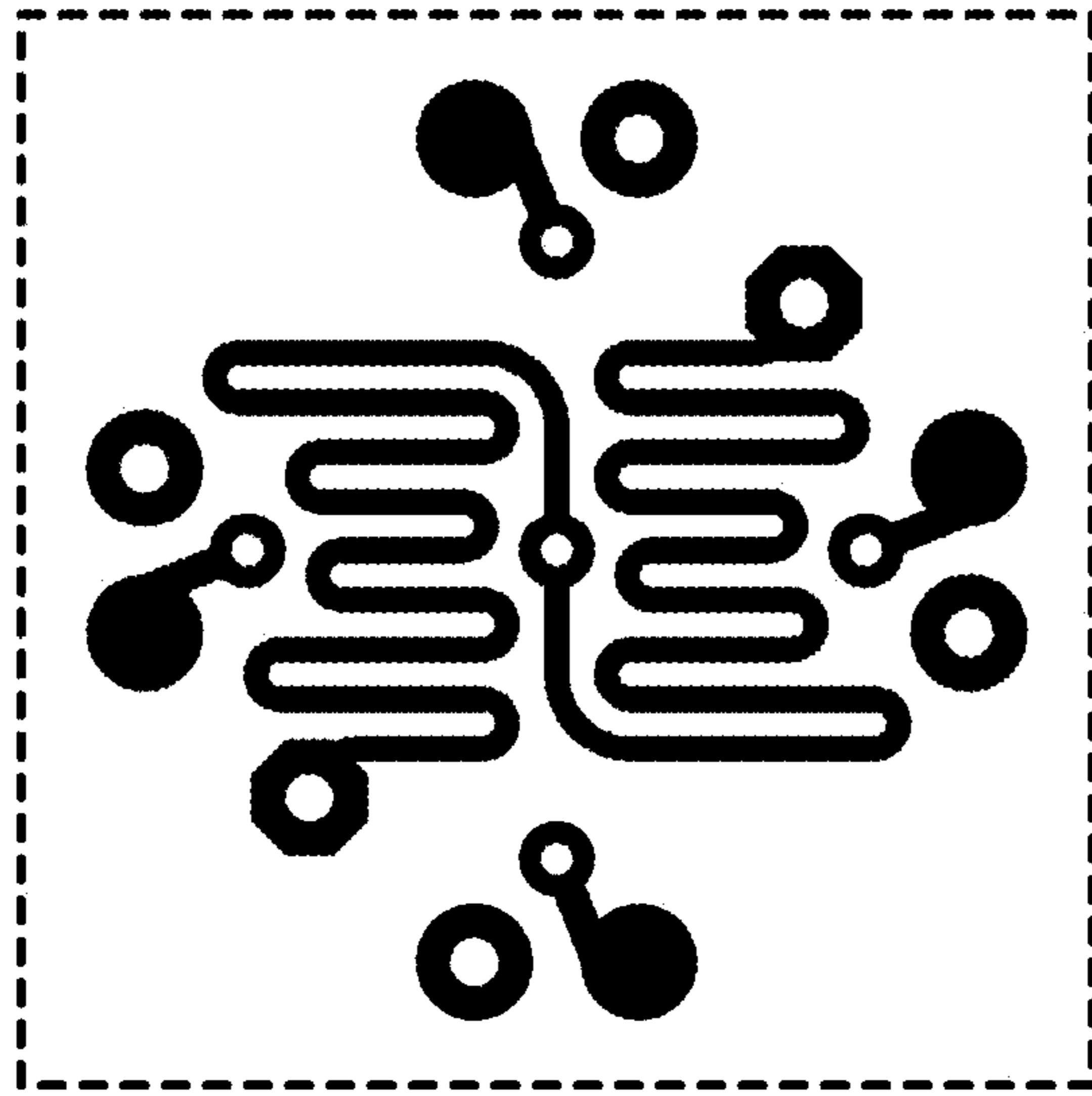


FIG. 4



FIG. 5